

## LISTING OF CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) An image pick-up device comprising:

an image pick-up unit for capturing an optical image obtained from incident light entering ~~to the~~ an internal cavity ~~[[of]]~~ formed by a frame ~~which has the~~ having an inner surface and ~~[[the]]~~ an outer surface, and outputting an image signal of the optical image;

wiring extending from the image pick-up unit in an opposite direction to the direction in which the incident light enters, ~~which is the wiring being~~ capable of transmitting the image signal; and

a substrate ~~which is~~ disposed in a predetermined position within the internal cavity of the frame so as to hermetically seal one of a first opening and a second opening formed on the frame, ~~has the substrate having~~ engaging portions for engaging with the wiring, one surface of ~~which is the substrate being~~ substantially orthogonal to the axial direction of the frame, and ~~which is~~ formed of a member having a light-transmitting property.

2. (Original) The image pick-up device according to claim 1, wherein the engaging portions are holes into which the wiring can be inserted.

3. (Currently Amended) The image pick-up device according to claim 1, wherein ~~the substrate is disposed in a predetermined position within the internal cavity of the frame so as to hermetically seal one of the openings of the frame, and wiring patterns are provided on the surface of the substrate on a proximal face the opening side for electrically connecting the engaging portions to the wiring.~~

4. (Currently Amended) The image pick-up device according to claim 1 ~~[[3]]~~, wherein the substrate is joined hermetically to the inner surface of the frame by soldering.

5. (Currently Amended) An image pick-up device comprising:

image pick-up means for capturing an optical image obtained from incident light entering ~~to the~~ an internal cavity ~~[[of]]~~ formed by a frame, and outputting an image signal of the optical image;

wiring means extending from the image pick-up means in an opposite direction to the direction in which the incident light enters, which are capable of transmitting the image signal; and

a substrate ~~which is~~ disposed in a predetermined position within the internal cavity of the frame so as to hermetically seal one of a first opening and a second opening formed on the frame, ~~[[has]]~~ the substrate having engaging portions for engaging with the wiring means, one surface of ~~which is~~ the substrate being substantially orthogonal to the axial direction of the frame, and ~~which is~~ formed of a member having a light-transmitting property.

6. (Currently Amended) An endoscope having an insertion portion which can be inserted into a body to be examined, comprising:

an image pick-up unit for capturing an optical image obtained from incident light entering ~~to the~~ an internal cavity ~~[[of]]~~ formed by a frame provided on a front end portion of the insertion portion, and outputting an image signal of the optical image;

wiring extending from the image pick-up unit in an opposite direction to the direction in which the incident light enters, which is capable of transmitting the image signal; and

a substrate ~~which is~~ disposed in a predetermined position within the internal cavity of the frame so as to hermetically seal one of a first opening and a second opening formed on the frame, ~~has~~ the substrate having engaging portions for engaging with the wiring, one surface of ~~which is~~ the substrate being substantially orthogonal to the axial direction of the frame, and ~~which is~~ formed of a member having a light-transmitting property.

7. (Original) The endoscope according to claim 6, wherein the engaging portions are holes into which the wiring can be inserted.

8. (Currently Amended) The endoscope according to claim 6, wherein ~~the substrate is disposed in a predetermined position within the internal cavity of the frame so as to hermetically seal one of the openings of the frame, and~~ wiring patterns are provided on the surface of the substrate on a proximal face ~~the opening side~~ for electrically connecting the engaging portions to the wiring.

9. (Currently Amended) The endoscope according to claim 6, wherein the substrate is joined hermetically to ~~[[the]]~~ an inner surface of the frame by soldering.

10. (Currently Amended) An endoscope having an insertion portion which can be inserted into a body to be examined, comprising:

image pick-up means for capturing an optical image obtained from incident light entering ~~to the~~ an internal cavity ~~[[of]]~~ formed by a frame provided on a front end portion of the insertion portion, and outputting an image signal of the optical image;

wiring means extending from the image pick-up means in an opposite direction to the direction in which the incident light enters, ~~which are~~ the wiring means being capable of transmitting the image signal; and

a substrate ~~which is~~ disposed in a predetermined position within the internal cavity of the frame so as to hermetically seal one of a first opening and a second opening formed on the frame, ~~[[has]]~~ the substrate having engaging portions for engaging with the wiring means, one surface of ~~which is~~ the substrate being substantially orthogonal to the axial direction of the frame, and ~~which is~~ formed of a member having a light-transmitting property.

11. (Currently Amended) An assembly method for an image pick-up device comprising an image pick-up unit for capturing an optical image obtained from incident light and outputting an image signal of the optical image, comprising the steps of:

disposing a substrate formed of a transparent member on the rear end of an internal cavity of a substrate frame such that one surface thereof is substantially orthogonal to ~~[[the]]~~ an axial direction of the substrate frame, and hermetically joining ~~[[the]]~~ an inner peripheral surface of the substrate frame and ~~[[the]]~~ an outer peripheral surface of the substrate;

engaging wiring of a solid-state image pick-up device provided in the image pick-up unit, which extends in an opposite direction to the direction in which the incident light enters, with a plurality of first engaging portions provided in the substrate while performing position alignment visually;

joining the engaging portions and wiring hermetically;

joining the inner surface of the substrate frame and ~~[[the]]~~ an outer surface of a lens holder of the image pick-up unit hermetically;

engaging cable signal lines inserted into the cable holder with ~~other~~ a plurality of second engaging portions in the substrate from an opposite direction to the direction in which the plurality of first engaging portions are engaged with the substrate; and

joining the ~~other~~ plurality of second engaging portions and the cable signal lines hermetically.

12. (Currently Amended) The assembly method for an image pick-up device according to claim 11, wherein the plurality of first engaging portions and ~~other~~ plurality of second engaging portions are holes into which the wiring and the cable signal lines can be respectively inserted.

13. (Currently Amended) The assembly method for an image pick-up device according to claim 11, wherein the substrate comprises wiring patterns for electrically connecting the plurality of first engaging portions and ~~other~~ the plurality of second engaging portions on the surface of the substrate on ~~[[the]]~~ a side at which the cable signal lines are engaged with the substrate.

14. (Currently Amended) The assembly method for an image pick-up device according to claim 11, wherein the substrate is hermetically joined to ~~[[the]]~~ an inner surface of the substrate frame by brazing.

15. (Currently Amended) The assembly method for an image pick-up device according to claim 11, wherein wiring is hermetically joined to the plurality of first engaging portions and the cable signal lines are hermetically joined to the ~~other~~ plurality of second engaging portions by brazing.

16. (Currently Amended) An assembly method for an image pick-up device comprising an image pick-up unit for capturing an optical image obtained from incident light and outputting an image signal of the optical image, comprising the steps of:

engaging cable signal lines inserted into a cable holder with a plurality of first engaging portions provided on a substrate formed of a transparent member;

joining the engaging portions and cable signal lines hermetically;

disposing the substrate on ~~[[the]]~~ a rear end of a substrate frame such that one surface thereof is substantially orthogonal to ~~[[the]]~~ an axial direction of the substrate frame, and hermetically joining ~~[[the]]~~ an inner surface of the substrate frame and ~~[[the]]~~ an outer surface of the substrate;

engaging wiring of a solid-state image pick-up device provided in the image pick-up unit, which extends in an opposite direction to the direction in which the incident light enters, with ~~other~~ a plurality of second engaging portions provided in the substrate while performing position alignment visually;

joining the ~~other~~ plurality of second engaging portions and wiring hermetically; and

joining the inner peripheral surface of the substrate frame and ~~[[the]]~~ an outer surface of a lens holder of the image pick-up unit hermetically.

17. (Currently Amended) The assembly method for an image pick-up device according to claim 16, wherein the plurality of first engaging portions and ~~other~~ plurality of second engaging portions are holes into which the wiring and the cable signal lines can be respectively inserted.

18. (Currently Amended) The assembly method for an image pick-up device according to claim 16, wherein the substrate comprises wiring patterns for electrically connecting the plurality of first engaging portions and ~~other~~ plurality of second engaging portions on the surface of the substrate on the side at which the cable signal lines are engaged with the substrate.

19. (Currently Amended) The assembly method for an image pick-up device according to claim 16, wherein the substrate is hermetically joined to the inner surface of the substrate frame by brazing.

20. (Currently Amended) The assembly method for an image pick-up device according to claim 16, wherein wiring is hermetically joined to the plurality of first engaging portions and the cable signal lines are hermetically joined to the ~~other~~ plurality of second engaging portions by brazing.